AMTECH

COMPANY INTRODUCTION

NASDAQ: ASYS

November 2026



Safe Harbor Statement

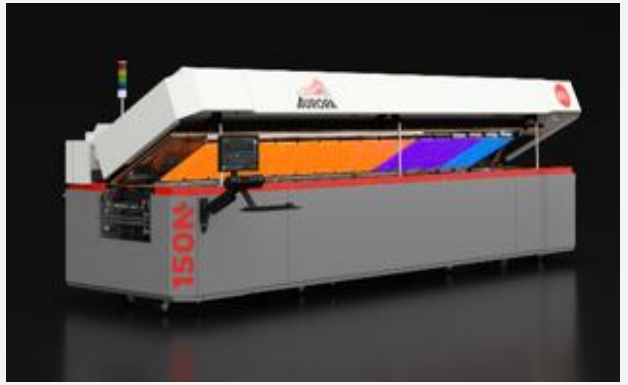
This Presentation may contain certain statements or information that constitute “forward-looking statements” (as such term is defined in Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended, and the Private Securities Litigation Reform Act of 1995). In some, but not all, cases, forward-looking statements can be identified by terminology such as “may,” “plan,” “anticipate,” “seek,” “will,” “expect,” “intend,” “estimate,” “anticipate,” “believe,” “continue,” “predict,” “potential,” “project,” “should,” “would,” “could”, “likely,” “future,” “target,” “forecast,” “goal,” “observe,” and “strategy” or the negative of these terms or other comparable terminology. Examples of forward-looking statements include statements regarding Amtech System, Inc.’s (“Amtech” or the “Company”) future financial results, operating results, business strategies, projected costs, products under development, competitive positions, plans and objectives of Amtech and its management for future operations, efforts to improve operational efficiencies and effectiveness and profitably grow our revenue, and enhancements to our technologies and expansion of our product portfolio. Such forward-looking statements and information are provided by the Company based on current expectations of the Company and reflect various assumptions of management concerning the future performance of the Company, and are subject to significant business, economic and competitive risks, uncertainties and contingencies, many of which are beyond the control of the Company. Accordingly, there can be no guarantee that such forward-looking statements or information will be realized. Actual results may differ materially from historical results and expectations based on forward-looking statements made in this document or elsewhere by Amtech or on its behalf. No representations or warranties are made as to the accuracy or reasonableness of any expectations or assumptions or the forward-looking statements or information based thereon. Each recipient of forward-looking statements should make an independent assessment of the merits of and should consult its own professional advisors. Except as required by law, we undertake no obligation to publicly update forward-looking statements, whether as a result of new information, future events, or otherwise. These forward-looking statements speak only as of the date of this Presentation. Except as required by any applicable law or regulation, the Company expressly disclaims any obligation or undertaking to release publicly any updates or revisions to any forward-looking statements contained herein to reflect any change in the Company’s expectations with regard thereto or any change in events, conditions or circumstances on which any such statement is based.

Enabling AI Semiconductor Packaging and Advanced Semiconductor Fabrication

Amtech provides differentiated thermal equipment for advanced packaging interconnects used for AI devices, datacenters and electronics assemblies as well as specialty chemistry, foundry services and services and consumables to the semiconductor industry.

- Strong growth driven by AI advanced packaging applications
- Established global technology leadership
- Capital efficient and scalable semi-fabless manufacturing model
- Focus on driving profitable growth and high returns on capital employed to create shareholder value
- Significant cash balance of $83M





NASDAQ: ASYS | 40+ Years | 4 Manufacturing Locations | Global Customer Base

AMTECH REPORTING DIVISIONS

Two Reporting Segments with Complementary Growth Drivers

~80% Thermal Processing Solutions

Primary growth engine driven by AI and advanced packaging

Advanced thermal-processing equipment for AI infrastructure.

- Reflow ovens and controlled-atmosphere furnaces
- Advanced packaging and high-performance electronics
- Parts, upgrades and aftermarket services

BTU AN AMTECH COMPANY

TPS: Secular equipment growth

~20% Semiconductor Fabrication Solutions

Recurring revenue platform with new formulation opportunities

Equipment, specialty chemistries, consumables and services supporting critical semiconductor-fabrication processes.

- Lapping, polishing and cleaning consumables
- CMP parts, upgrades and refurbishment
- Wafer-cleaning equipment and process development

PR HOFFMAN AN AMTECH COMPANY

INTERSURFACE DYNAMICS AN AMTECH COMPANY

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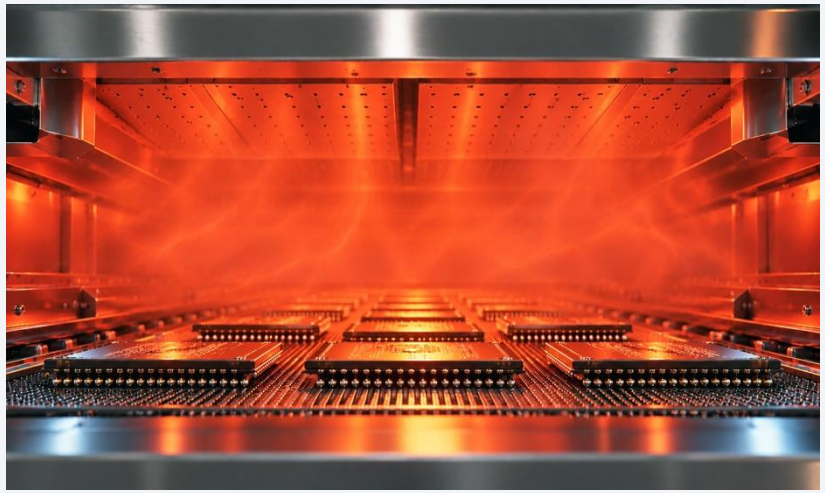
SFS: Recurring consumables and services

World Leader in Reflow for Advanced Packaging

Flip Chip • 2.5D • CoWoS • Panel Packaging • Co-Packaged Optics

As AI and high-performance computing push the limits of semiconductor design, BTU's Aurora and Pyramax meet the challenge with unmatched thermal precision and process control.

- **Ultra-low oxygen reflow.** Single-digit ppm O_2 above source for sensitive solder joints and exposed copper.
- **Exceptional thermal uniformity.** Industry-leading convection rates deliver tight delta T.
- **Slow programmable cooling.** Mitigates CTE mismatch, preventing warpage and microcracking.
- **Optional TrueFlat™ warpage control.** For ultra-thin substrates where planarity is critical to yield.
- **Configurable architecture, MES integration.** Production-proven in the most demanding environments.



BTU's Aurora and Pyramax deliver unmatched thermal precision and process control for AI and high-performance computing.

AURORA VACUUM

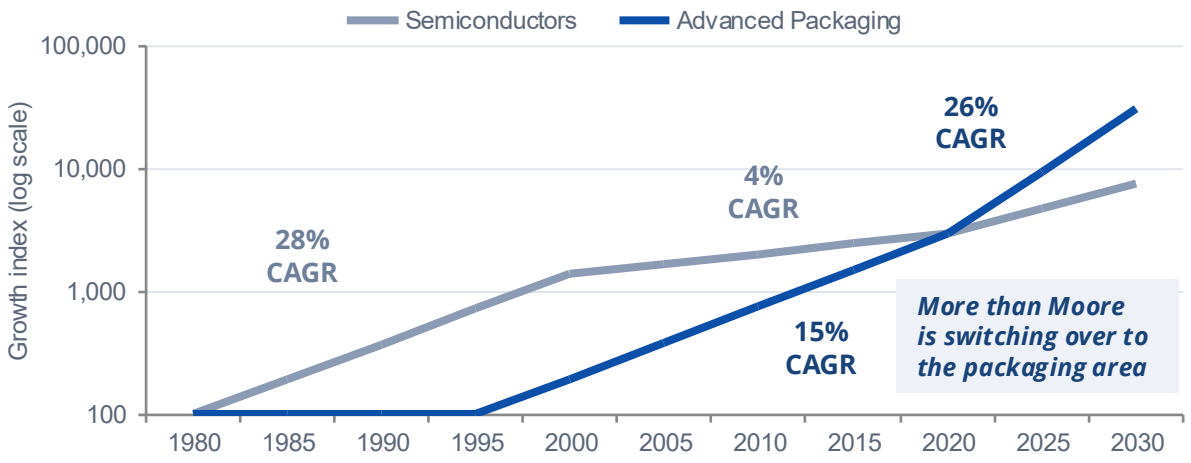
Pyramax WITH TrueFlat TECHNOLOGY

BTU AN AMTECH COMPANY

Growth through Value Migration: Silicon to Package

- Scaling devices to half the size at double the speed is no longer economical at the silicon level; ***value has migrated to advanced packaging***
- Recent AI products deliver faster performance, lower cost, smaller size and faster time to market through heterogeneous integration
- Advanced packaging is not close to diminishing returns, per the industry's 5-year roadmap (CoWoS to CoPoS to advanced substrates)
- Next package-level bottleneck: faster communication through the transition from copper to optics (Co-Packaged Optics, CPO)

Growth Index: Semiconductors vs. Advanced Packaging (1980–2030)



>35x
faster performance
NVIDIA H200 (2023): 128 GB/s → 4.8 TB/s

~50%
lower cost
AMD Ryzen 16-core (2022): $140 → $68

60%
reduced area
Infineon Optireg (2020): 10.9 → 4.0 mm²

75%
faster time to market
Intel HPC (2023): 4 years → 1 year

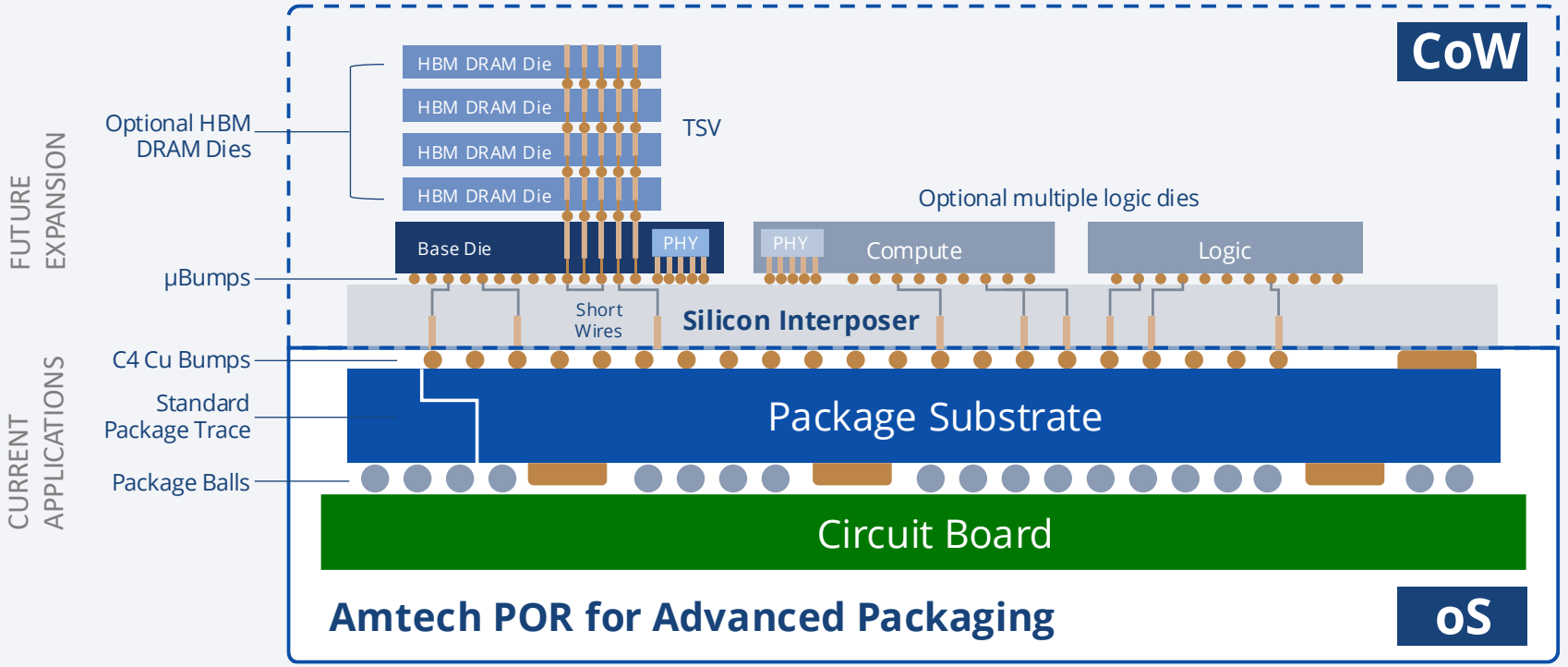
Similar growth roadmap to the Semiconductor Market forecasted for Advanced Packaging

CoWoS ARCHITECTURE

Multiple Interconnect Layers Available to Reflow in the Advanced Package

Newly introduced and existing additional package layers require multiple reflow and curing steps, creating adjacent opportunities for Amtech's thermal-processing technologies.

Several targeted applications represent addressable markets larger than Amtech's current served market, offering meaningful growth vectors independent of and additive to Advanced Packaging market growth.

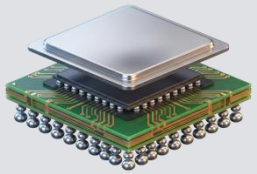


Advanced Packaging Technologies Are Not Equal

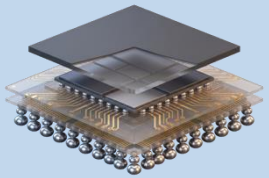
The industry is advancing along parallel fan-out, 2.5D and 3D paths, with optics integrated at the system level

Optical integration can be added to advanced package architectures

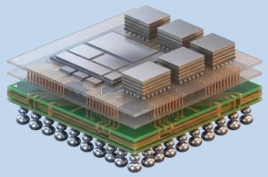
CONVENTIONAL ASSEMBLY	FAN-OUT	2.5D INTEGRATION	3D STACKING	SYSTEM-LEVEL INTEGRATION
SMT / EMS	**InFO**	**CoWoS-R**	**Foveros**	**System-on-Wafer**
FCBGA / Flip Chip	FO-WLP / FOCoS	**CoWoS-S / CoWoS-L**	SoIC	CoPoS / panel scale
	FOPLP	EMIB	Hybrid bonding	**CPO-enabled systems**



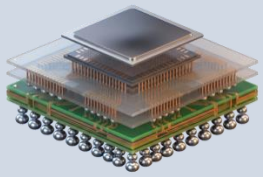
Board and package assembly



RDL on reconstituted wafer or panel

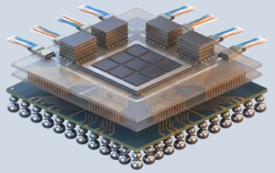


RDL, interposer or local silicon bridge



Vertical die-to-die integration

CPO is an integration layer, not a "4D" packaging generation.



Compute, memory and optical I/O

EMS / assemblers: Flex • Celestica

OSAT ecosystem: ASE / SPIL • Amkor • PTI • JCET

Foundry / IDM platforms: TSMC • Intel • Samsung

Increasing interconnect density, integration complexity and system value

Key Market Drivers – Advanced Packaging

AI DEMAND

3x Capex

Nvidia reported 3x capex by 2030 for AI/data center (23–40% CAGR)

CAPACITY BUILD-OUT

>20 New Projects

OSAT's new greenfield and brownfield fabs to double capacity by 2030

LEAP and CoWoS

80% CAGR

TSMC CoWoS growth through 2029. Co-Packaged Optics (CPO) adds optical integration

Rapid Prototyping

25–50%

Faster validation at TSMC's Kaohsiung 'mini loop' line. Industry pushing faster qualification to enable capacity growth faster

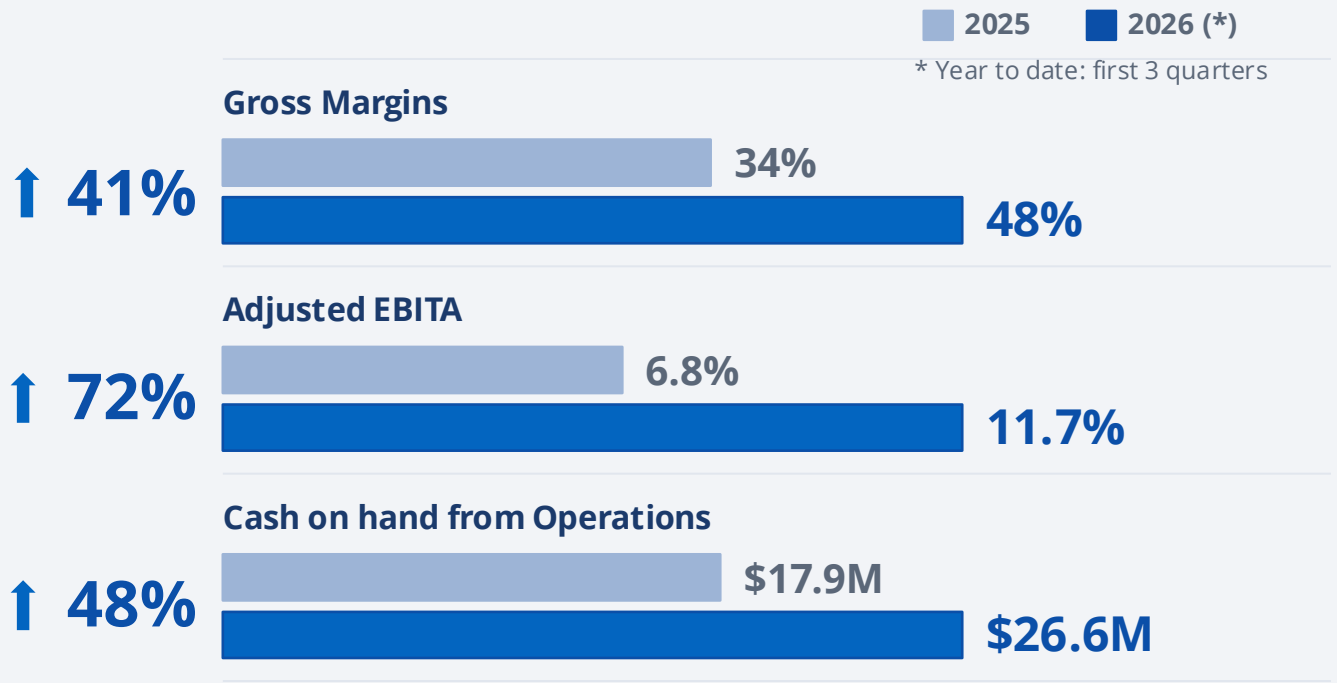
- **Advanced Packaging** growth continues at 10% CAGR on an aggregate basis
- **Leading Edge Advanced Packaging** growth outpaces industry growth at >25% till 2030
- **New Fabs** buildouts by OSATs continues to be a funded activity to drive 2x capacity for LEAP
- **AI** demand fundamentals remains strong driven by end market demand

POR ramp secured near term; innovation opens entry beyond

OPERATIONAL EFFICIENCY

Transformation to an Efficient, Scalable Operating Model

- Reduced structural costs and established a more scalable operating platform.
- Consolidated operational footprint: nine to four manufacturing sites
- Expanded capacity through outsourced partners in proximity to customers
- Optimized product portfolio to focus on profitable products

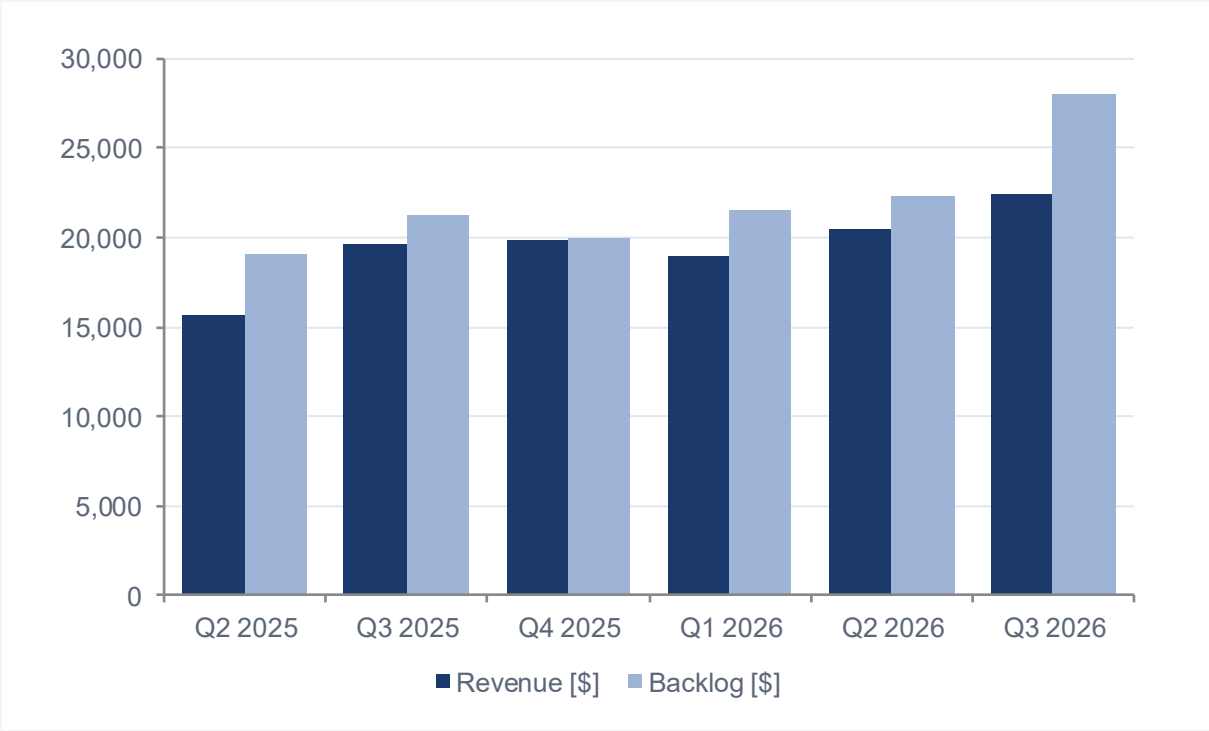


Total Cash Including Capital Raise (as of June 30th 2026 **$83.1M**

Revenue growth combined with higher gross margins flow to significantly higher profits and cash growth

Financial and Business Trends

- **Revenue** growth consistent with AI/Advanced Packaging end markets
- **Gross margin** growth from product mix and higher-end shipments for demanding applications
- **Bookings** outpacing revenue, indicating a longer-term growth cycle and healthier backlog
- **AI Growth** Large growth in data centers and advanced packaging supporting AI mega trend



Long-term trend of backlog, revenue and profitability growth

A Profitable, Small-cap growth Company enabling AI Advanced Packaging with a strong balance sheet and no debt.

1 Growth driven by AI advanced packaging

AI-related revenue up ~120% YoY, now >40% of TPS sales; BTU is the dominant process of record

2 Record OSAT / foundry capex tailwind

ASE and Amkor expanding 2026 capex as AI GPUs need 2–4x the packaging area

3 Differentiated technology moat

TrueFlat warpage control + industry-leading temperature uniformity win the most demanding AI packages

4 Accelerating orders = visibility

TPS book-to-bill 1.37x; bookings > sales for 3 straight quarters

5 Transformed, asset-light margin profile

Semi-fabless model: GM 50.0% vs. 41.5% a year ago; 11 straight quarters of positive operating cash flow

6 TAM expansion + fortress balance sheet

$83.1M cash, zero debt: dry powder for next-gen platforms and accretive M&A

Snapshot

As of 11/17/26

$11.36 Share price	**~$200M** Market cap
$83.1M Cash; zero debt As of 6/30/26	**~$117M** Enterprise value

~1.3x

EV / FQ3 run-rate sales

Fiscal Year 2026 Third Quarter Financial Results

AI Product Demand Continues to be Strong

Quarterly Orders Exceed Revenues

Gross Margin Improved to 50%, up 230 bps from 2Q26

Adjusted EBITDA Margin of Nearly 15%

11th Consecutive Quarter of Positive Operating Cash Flow

$5 Million Share Repurchase Plan in Place

Third Quarter Fiscal 2026 Financial and Operational Highlights

- Net revenue of $22.4 million
- Cash of $83.1 million
- Cash provided by operations of $1.1 million
- GAAP net income of $1.7 million
- Non-GAAP net income of $2.4 million (1)
- Adjusted EBITDA of $3.3 million (1)
- Customer orders of $28.8 million, up from $21.1 million in 2Q26
- Backlog of $28.7 million at end of June 2026, compared to $22.3 million at end of March 2026

(1) See GAAP to non-GAAP and EBITDA and Adjusted EBITDA reconciliation provided below

$60 Million Oversubscribed Public Offering of Common Stock -- 2,926,829 shares at $20.50 per share (June 3, 2026)

OUTLOOK

Fiscal Year 2026 Fourth Quarter Guidance

(period end 9/30/26)



- Revenues $22.5 – 24.0 Million
- Adjusted EBITDA margin in the low to mid-teens
- NOL valued at $74.3 million at 9/30/25

INVESTMENT OPPORTUNITY

Secular Growth for AI Semiconductor Device Packaging and Semiconductor Fabrication

Differentiated technology and strong market position in AI advanced packaging and electronic assembly applications with a highly scalable and capital efficient manufacturing model to create shareholder value

HARNESS GROWTH MARKETS

Market-leading products enabling scale in AI & e-mobility applications

OPERATING LEVERAGE

Committed to a disciplined approach to operations and scaled fixed costs

CASH FLOW GENERATION

Funds from operations strategically invested in growth

AMTECH | NASDAQ: ASYS



Backup

Experienced Management Team



Guy Shechter
President & Chief Executive Officer



Bob Daigle
Executive Chairman



Tom Sabol
Chief Financial Officer



Angi Larson
Chief Human Resource Officer



Jason Brown
Vice President and General Manager SFS, Global Operations



Rob DiMatteo
Vice President and General Manager, Thermal Processing Solutions

Navigating Innovation:
More than Century of Collective Expertise in Semiconductor, Electronics, and Advanced Materials Defines Our Executive Team

AMTECH SYSTEMS, INC.
(NASDAQ: ASYS)
(Unaudited)

Reconciliation of GAAP to Non-GAAP Financial Measures
($s in thousands)

	Three Months Ended			Nine Months Ended June 30,	
	June 30, 2026	March 31, 2026	June 30, 2025	2026	2025
Amtech Systems, Inc. Gross Profit:					
GAAP gross profit	$ 11,193	$ 9,769	$ 9,132	$ 29,456	$ 18,169
Inventory write-down of mature node semiconductor products	-	-	-	-	5,986
Non-GAAP gross profit	$ 11,193	$ 9,769	$ 9,132	$ 29,456	$ 24,155
GAAP gross margin	50%	48%	47%	48%	31%
Non-GAAP gross margin	50%	48%	47%	48%	41%
Thermal Processing Solutions Segment Gross Profit:					
GAAP gross profit	$ 9,006	$ 7,129	$ 6,325	$ 22,728	$ 14,005
Inventory write-down of mature node semiconductor products	-	-	-	-	3,562
Non-GAAP gross profit	$ 9,006	$ 7,129	$ 6,325	$ 22,728	$ 17,567
GAAP gross margin	51%	48%	45%	49%	32%
Non-GAAP gross margin	51%	48%	45%	49%	40%
Semiconductor Fabrication Solutions Segment Gross Profit:					
GAAP gross profit	$ 2,187	$ 2,640	$ 2,807	$ 6,728	$ 4,164
Inventory write-down of mature node semiconductor products	-	-	-	-	2,424
Non-GAAP gross profit	$ 2,187	$ 2,640	$ 2,807	$ 6,728	$ 6,588
GAAP gross margin	47%	46%	52%	44%	26%
Non-GAAP gross margin	47%	46%	52%	44%	41%

AMTECH SYSTEMS, INC.
(NASDAQ: ASYS)
(Unaudited)

Reconciliation of GAAP to Non-GAAP Financial Measures
(in thousands, except per share data)

	Three Months Ended			Nine Months Ended June 30,	
	June 30, 2026	March 31, 2026	June 30, 2025	2026	2025
Consolidated Net Income (Loss):					
GAAP net income (loss)	$ 1,658	$ 1,166	$ 106	$ 2,932	$ (31,394)
Disposal of fixed assets from sublease	83	-	-	83	-
ROU asset impairment	151	-	-	151	-
Inventory write-down of mature node semiconductor products	-	-	-	-	5,986
Amortization of acquired intangible assets	27	27	27	81	242
Stock compensation expense	394	328	338	971	961
Goodwill impairment	-	-	-	-	20,353
Intangible asset impairment	-	-	-	-	2,569
Severance expense	50	-	421	50	678
Non-GAAP net income (loss)	$ 2,363	$ 1,521	$ 892	$ 4,268	$ (605)
Net Income (Loss) per Diluted Share:					
GAAP net income (loss) per diluted share	$ 0.10	$ 0.08	$ 0.01	$ 0.19	$ (2.20)
Disposal of fixed assets from sublease	0.01	-	-	0.01	-
ROU asset impairment	0.01	-	-	0.01	-
Inventory write-down of mature node semiconductor products	-	-	-	-	0.42
Amortization of acquired intangible assets	-	-	-	0.01	0.02
Stock compensation expense	0.02	0.02	0.02	0.06	0.07
Goodwill impairment	-	-	-	-	1.42
Intangible asset impairment	-	-	-	-	0.18
Severance expense	-	-	0.03	-	0.05
Non-GAAP net income (loss) per diluted share	$ 0.14	$ 0.10	$ 0.06	$ 0.28	$ (0.04)

AMTECH SYSTEMS, INC.
(NASDAQ: ASYS)
(Unaudited)

Reconciliation of Net Income to EBITDA and Adjusted EBITDA
(in thousands, except per share data)

	Three Months Ended			Nine Months Ended June 30,	
	June 30, 2026	March 31, 2026	June 30, 2025	2026	2025
Amtech Systems, Inc. EBITDA:					
GAAP net income	$ 1,658	$ 1,166	$ 106	$ 2,932	$ (31,394)
Interest income	(273)	(116)	(88)	(504)	(119)
Interest expense	2	8	5	18	19
Income tax provision	616	502	799	1,699	1,516
Depreciation and amortization expense	620	627	594	1,861	2,167
EBITDA	2,623	2,187	1,416	6,006	(27,811)
Disposal of fixed assets from sublease	83	-	-	83	-
ROU asset impairment	151	-	-	151	-
Inventory write-down of mature node semiconductor products	-	-	-	-	5,986
Stock compensation expense	394	328	338	971	961
Goodwill impairment	-	-	-	-	20,353
Intangible asset impairment	-	-	-	-	2,569
Severance expense	50	-	421	50	678
Adjusted EBITDA	$ 3,301	$ 2,515	$ 2,175	$ 7,261	$ 2,736



End